technical specification

NO CLEAN SOLDER WIRE
0.50MM – 1.60MM

FEATURES

- No need for cleaning
- Virgin raw materials
- High insulation resistance
- Excellent wetting
- Void free flux core
- Solidifies quickly & consistently

DESCRIPTION

Techmet **No Clean Flux Core Solder wire** is a 63% tin based solder, manufactured in accordance with SABS requirements from only virgin raw materials to meet most international specifications. Therefore consistency and quality of the solder can be guaranteed.

The no clean core has an activity level, the same as RMA. Leaves a **clear slightly amber no clean residue**. Residue has a SIR(surface insulation resistance) of 1.5 x $10^{(10)}$ohm and is excellent for SMT touch up and repair. The product is offered at 1 to 2 flux percentage. The residue is solvent soluble if cleaning is necessary. The core is completely free of voids.

The unique no clean flux combination contains no halides, have no noticeable odour, and wet and spread as well as rosin cored solders.

Very little smoke is generated during soldering and with no unpleasant odour, oxides or hazardous gasses.

BENEFITS

- International specifications
- No clean residue
- Over 85% spreading
- No noticeable odour
- Very little smoke
- Consistent melting range

SPECIFICATION

Tin	63%
Lead	37%
Diameter	0.5 to 1.6 mm
Flux content	1.5% (0.1%Tol.)
Chlorides	less than 0.05%.
Copper test	passes
Melting point	183ºC
J-STD-004	ROL1

Roll size : 500 gram per roll

Packing : 5 Kg boxes (10 rolls)

Techmet

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